

## PRESS RELEASE

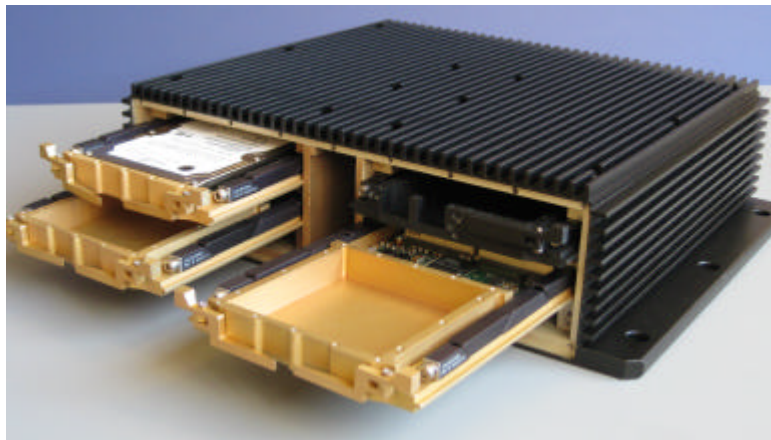
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**PCI -SYSTEMS Inc.**

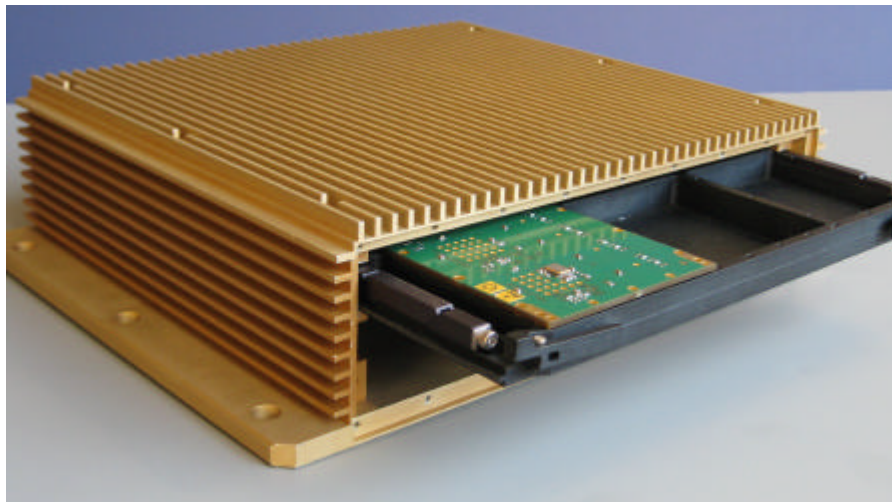
### **LOW COST VPX Conduction Cooled Rugged NEMA 4x Enclosures**

Laurel, MD and Dietzenbach, Germany

November 1 , 2008—**PCI -SYSTEMS Inc.** , a leading supplier of conduction cooled systems , today announced **NEW LOW COST VPX Conduction Cooled Rugged Enclosures**, enabling accelerated development of rugged conduction cooled embedded systems.



**3U, 4 slot NEMA 4x enclosure with power supply slot**



**6U, 2 slot NEMA 4x enclosure with power supply**

**PCI -SYSTEMS Inc.** manufactures a variety of COTS modular designed conduction cooled chassis for VPX, VME, CPC1 and CPC1express applications.

Two level maintenance models include 3U, 6U, ATR, ARINC600 and custom chassis and all are available with interchangeable backplane-bus versions.

## **The chassis are manufactured using extruded aluminium --- the result is a very low cost design.**

Also, during development, each slot has its own rear I/O PCB to ease definition and testing of the final custom wiring. This setup can be easily exchanged with a custom rear I/O PCB set.

Therefore cost of ownership is minimized, since development and production versions of the chassis have the same basic design components.

VPX versions are available with a PCIe bus implementation on the backplane, having up to 8 lanes per slot and a PCIe lane switch.

Current CPU boards are available with x4 or x8 lane PCIe configuration and include a Intel core duo board based on the Intel 3100 chipset with ECC and a Freescale MPC8572E CPU dual core PowerPC processor board.

backplane will accommodate the Modular PS, a one slot width CPU, and 5 add-on card slots.

## **CompactPCI Express Type 3, CompactPCI and VPX backplanes with Rear I/O are available.**

**PCI - SYSTEMS Inc.** unique Compact PCI Express Type 3 backplane has the same full rear I/O capability as CompactPCI with PCIe 4x lanes of bandwidth.

Rear I/O transition modules are standard. The rear panel can be easily customized to adapt to your rugged application. Also this chassis may be easily customized for fewer slots to reduce width and the rear I/O may be modified to reduce depth for special applications. The chassis is manufactured from aluminum to guarantee maximum ruggedness at minimum weight. Power dissipation of the installed boards and power supply is by conduction cooling through the walls of the chassis and cooling fins.

Boards are fixed in place with wedge locks to insure good heat conduction to the chassis and vibration control. This is an ideal solution as a hardware/software development platform and can be easily upgraded for full rugged projects.

**PCI - SYSTEMS Inc.** manufactures a variety of conduction cooled carrier boards for different bus architectures and can customize mechanical shapes and layout changes even for small quantities with fast turnaround times.

"Very few high volume applications can justify the design of a custom conduction cooled chassis, stated Claus Gross, President of **PCI - SYSTEMS Inc.** "For cost reasons the majority of designs must utilize a modular design made with off-the-shelf components."

Until recently, Mr. Gross explained, OEM's had to design a chassis by immediately using customized rear I/O.

Many designers had to design their own backplane into their application, in spite of the extended design time.

"With our modular approach of delivering exchangeable backplane types, the migration path from prototyping to a mission computer is done very fast" he stated, "designers have a magnificent choice: combine a proven low cost mechanical subsystem and basic electronics like carriers for XMC-PMC cards and a power supply without packaging or form-factor constraints to their application."

**PCI - SYSTEMS Inc.** develops and manufactures intelligent CPU and peripheral boards as well as advanced mechanical design solutions in the US and Germany for many platforms that provide precision control of robotic and automated equipment in the semiconductor, medical and industrial equipment markets as well as for ruggedized embedded OEM applications in airborne and defense applications.

## **Contact:**

### **USA**

**PCI-Systems Inc.**  
13 C Street, Suite D  
Laurel, MD 20707  
Tel: (301) 362-1233

### **Europe**

**PCI embedded computer systems GmbH**  
Lehrstr.31  
D-63128 Dietzenbach  
Tel: xx-0-6074-35108  
FAX: xx-0-6074-35114

Please enquire to [sales@pcisystems.com](mailto:sales@pcisystems.com)

**Website** [www.pcisystems.com](http://www.pcisystems.com)

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